

PCN #207
Notification Date:
March 1, 2021

Product / Process Change Notice

Parts Affected:

The following SOT-223 transistors are affected:

CBCP69

CEN1220

CZT3019

Extent of Change:

The die attach method used in the assembly process is changing from eutectic to soft solder.

Reason for Change:

The soft solder die attach method is better suited for devices of larger die size.

Effect of Change:

This change does not affect the fit, form or function of the devices.

Qualification:

Test	Condition	Duration	Failure rate
Temperature Cycling (T.C.)	TA= -55+0°C/-10°C 15min(Min) TA= +150+15°C/-0°C 15min(Min) Transfer time less than 1min. The load should reach temp. within 15min	1000 Cycles	0/77
Resistance to Solder Heat (R.S.H.)	T =260°C ±5°C Dwell time = 10 sec.	1 Cycle	0/5
Thermal Shock Test (T.S.T.)	TA=0°C (5 min) ~ +100°C (5 min)	100 Cycles	0/77

Effective Date of Change:

Existing inventory will be shipped until depleted.

Sample Availability:

Please contact your salesperson or manufacturer's representative for samples.



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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	